

Structure and Process for Packaging Back-to-Back Chips

Abstract

5 A packaging structure for back-to-back chips, which includes: a
substrate, a first chip, a second chip, and an encapsulation. Wherein, the
first chip has an active side and an inactive side, and the active side of the
first chip is connected to the substrate by an adhesion layer and conducted
electrically with the substrate by wire-bonding. The second chip has an
10 active side that is also conducted electrically with the substrate by
wire-bonding and an inactive side that is connected to the inactive side of
the first chip by another adhesion layer. The encapsulation covers both the
first chip and the second chip for protecting the back-to-back packaging
structure.